Board Characteristics:
- All dimensions are given in inches unless specified otherwise.
- Material FR4 with Tg > 170°C, E.g. FR406.
- Minimum trace width: 0.006" and clearance: 0.005" on Signal_1,6 (Top and Bottom).
- 1 oz copper for all power layers and for Signal_1,2 (Top and Bottom).
- 1/2 oz copper for Stripline trace layers (Signal_2,3,4,5,7,8,9,10).
- Immersion Gold over copper, with min. Ni: 2.5-5 um; Au: 0.05-0.2 um.
- Apply Solder Mask over bare copper.
- Board Thickness: 0.093 +/- 0.008.
- Mill the Top and Bottom of board on the solder side to a thickness of 0.063" +/- 0.008.
- Silkscreen on Component and Solder Sides.
- 45 degree chamfer.
- FHS tolerances: +/- 0.002 unless specified otherwise.
- Interlayer spacing as specified.
- 2oz50 Ohm 4/ - 5 Ohm for 0.005" Stripline and 0.006" microstrip traces on all layers.
- Perform TDR test for all signal layers.
- Present TDR test results for all signal layers.